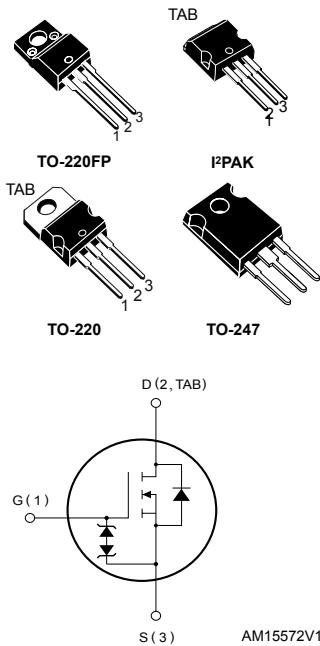


**N-channel 600 V, 0.108 Ω typ., 26 A, MDmesh M2 Power MOSFETs  
in TO-220FP, I<sup>2</sup>PAK, TO-220 and TO-247 packages**



## Features

Order codes	V <sub>DS</sub> @ T <sub>Jmax</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>	Package
STF33N60M2	650 V	0.125 Ω	26 A	TO-220FP
STI33N60M2				I <sup>2</sup> PAK
STP33N60M2				TO-220
STW33N60M2				TO-247

- Extremely low gate charge
- Excellent output capacitance (C<sub>oss</sub>) profile
- 100% avalanche tested
- Zener-protected

## Applications

- Switching applications
- LLC converters, resonant converters

## Description

These devices are N-channel Power MOSFETs developed using the MDmesh M2 technology. Thanks to their strip layout and improved vertical structure, these devices exhibit low on-resistance and optimized switching characteristics, rendering them suitable for the most demanding high-efficiency converters.



Product status links
<a href="#">STF33N60M2</a>
<a href="#">STI33N60M2</a>
<a href="#">STP33N60M2</a>
<a href="#">STW33N60M2</a>

## 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220FP	I <sup>2</sup> PAK, TO-220, TO-247	
V <sub>GS</sub>	Gate-source voltage	±25		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	26 <sup>(1)</sup>	26	A
	Drain current (continuous) at T <sub>C</sub> = 100 °C	16 <sup>(1)</sup>	16	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	104 <sup>(1)</sup>	104	A
P <sub>TOT</sub>	Total power dissipation at T <sub>C</sub> = 25 °C	35	190	W
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	15		V/ns
dv/dt <sup>(4)</sup>	MOSFET dv/dt ruggedness	50		V/ns
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s, T <sub>C</sub> = 25 °C)	2500		V
T <sub>stg</sub>	Storage temperature range	-50 to 150		°C
T <sub>j</sub>	Operating junction temperature range			

1. Limited by maximum junction temperature.
2. Pulse width is limited by safe operating area.
3. I<sub>SD</sub> ≤ 26 A, di/dt ≤ 400 A/μs, V<sub>DS peak</sub> < V<sub>(BR)DSS</sub>, V<sub>DD</sub> = 400 V
4. V<sub>DS</sub> ≤ 480 V

**Table 2. Thermal data**

Symbol	Parameter	Value			Unit
		TO-220FP	I <sup>2</sup> PAK TO-220	TO-247	
R <sub>thj-case</sub>	Thermal resistance junction-case	3.6	0.66		°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient	62.5		50	°C/W

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not repetitive (pulse width limited by T <sub>jmax</sub> )	5	A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	450	mJ

## 2 Electrical characteristics

( $T_C = 25^\circ\text{C}$  unless otherwise specified).

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	600			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_C = 125^\circ\text{C}$ <sup>(1)</sup>			100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$		0.108	0.125	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{\text{iss}}$	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	1781	-	pF
$C_{\text{oss}}$	Output capacitance		-	85	-	pF
$C_{\text{rss}}$	Reverse transfer capacitance		-	2.5	-	pF
$C_{\text{oss eq.}}$ <sup>(1)</sup>	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	135	-	pF
$R_G$	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ V}$	-	5.2	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 26 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$	-	45.5	-	nC
$Q_{gs}$	Gate-source charge	(see Figure 19. Test circuit for gate charge behavior)	-	9.9	-	nC
$Q_{gd}$	Gate-drain charge		-	18.5	-	nC

1.  $C_{\text{oss eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{\text{oss}}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 13 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	16	-	ns
$t_r$	Rise time	(see Figure 18. Test circuit for resistive load switching times and Figure 23. Switching time waveform)	-	9.6	-	ns
$t_{d(\text{off})}$	Turn-off delay time		-	109	-	ns
$t_f$	Fall time		-	9	-	ns

**Table 7. Source drain diode**

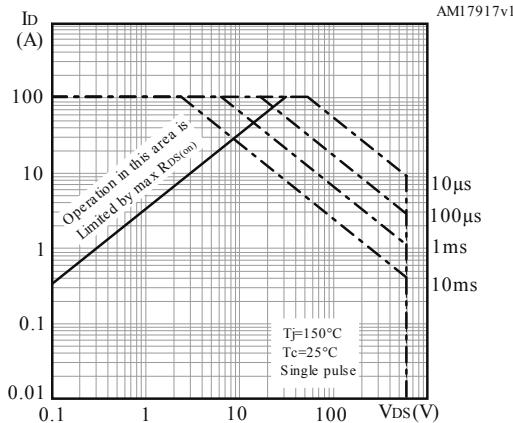
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		26	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		104	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 26 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 26 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	375		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ (see Figure 20. Test circuit for inductive load switching and diode recovery times)	-	5.6		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	$I_{SD} = 26 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ (see Figure 20. Test circuit for inductive load switching and diode recovery times)	-	30		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 26 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	478		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$ (see Figure 20. Test circuit for inductive load switching and diode recovery times)	-	7.7		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	$I_{SD} = 26 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ (see Figure 20. Test circuit for inductive load switching and diode recovery times)	-	35.5		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

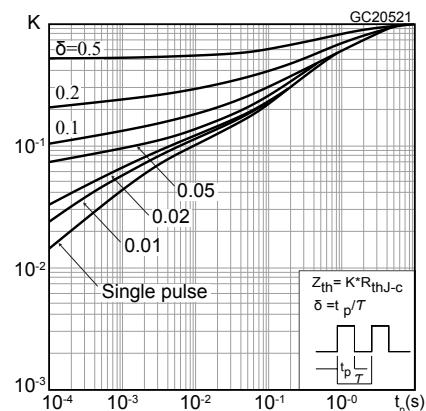
## 2.1

### Electrical characteristics (curves)

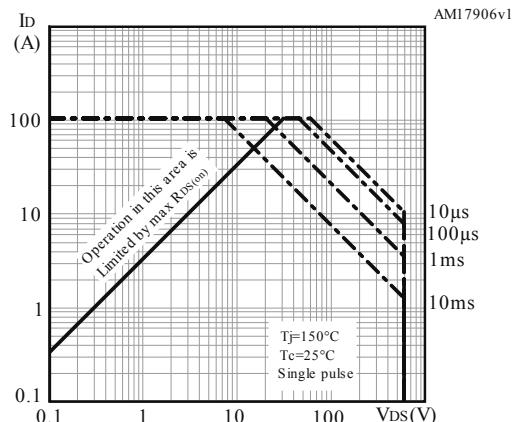
**Figure 1. Safe operating area for TO-220FP**



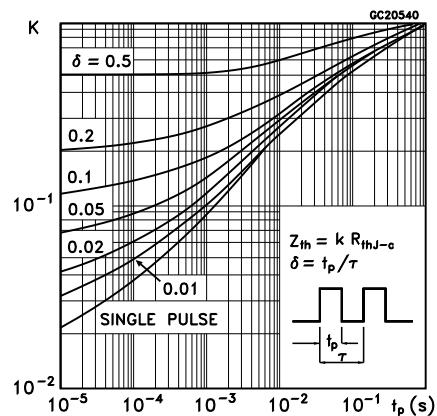
**Figure 2. Thermal impedance for TO-220FP**



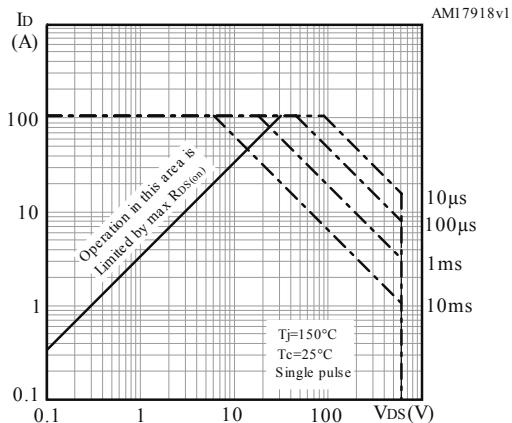
**Figure 3. Safe operating area for I<sup>2</sup>PAK and TO-220**



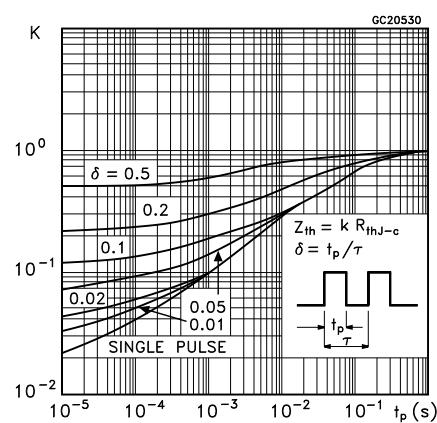
**Figure 4. Thermal impedance for I<sup>2</sup>PAK and TO-220**

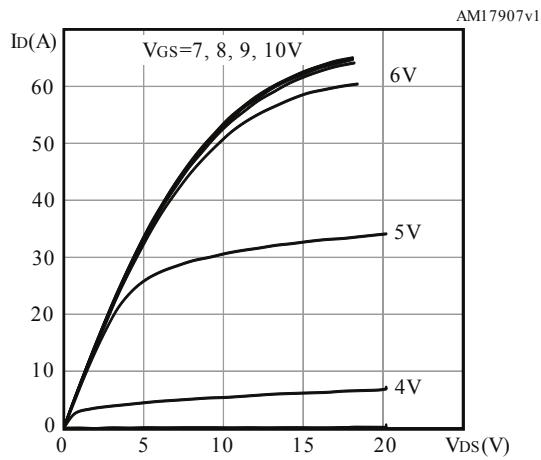
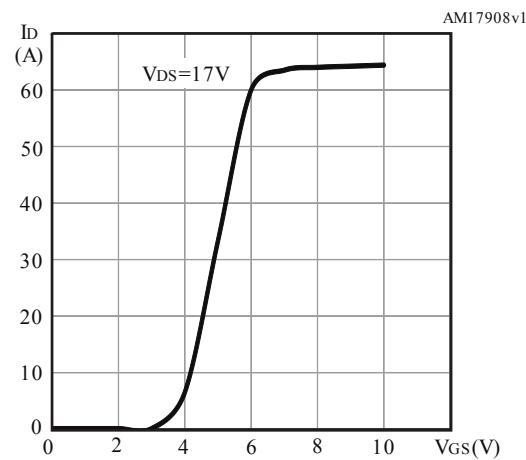
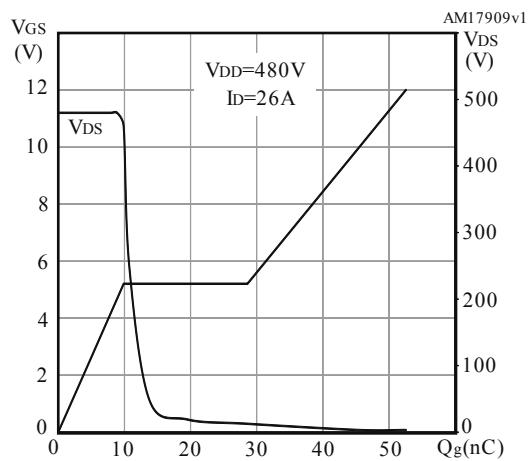
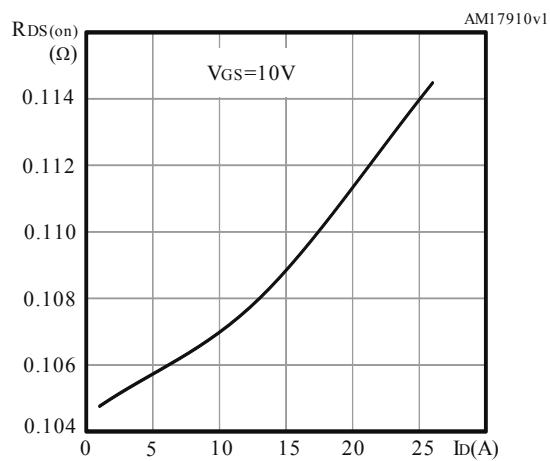
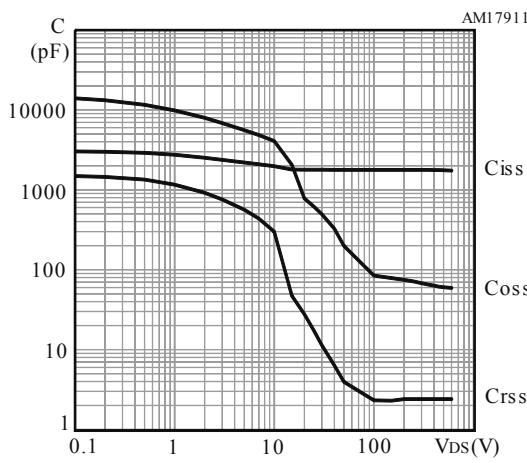
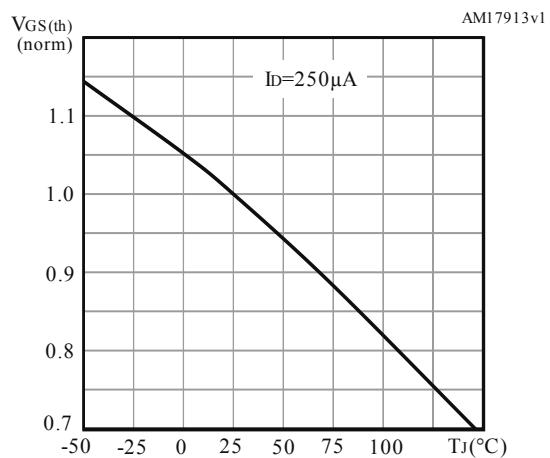


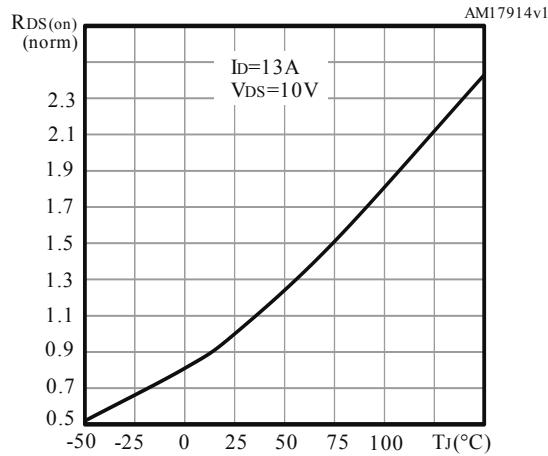
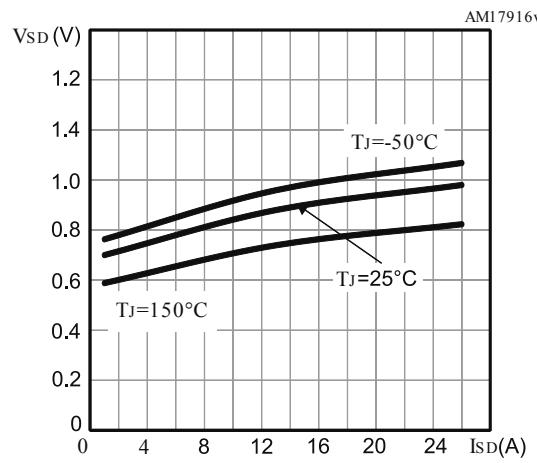
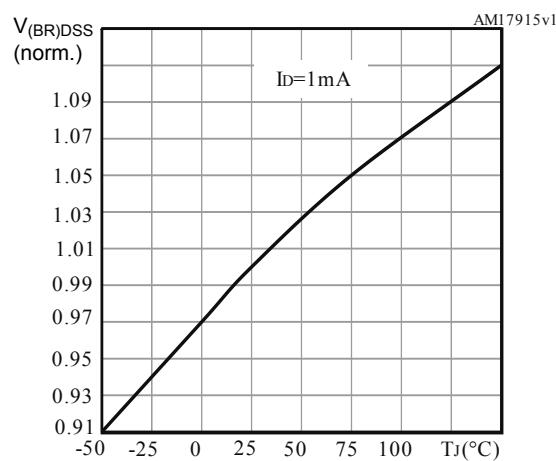
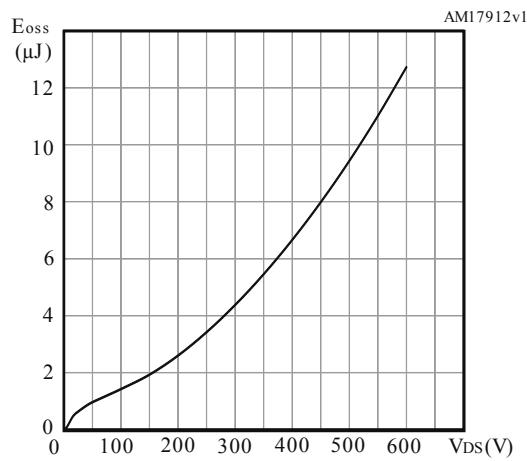
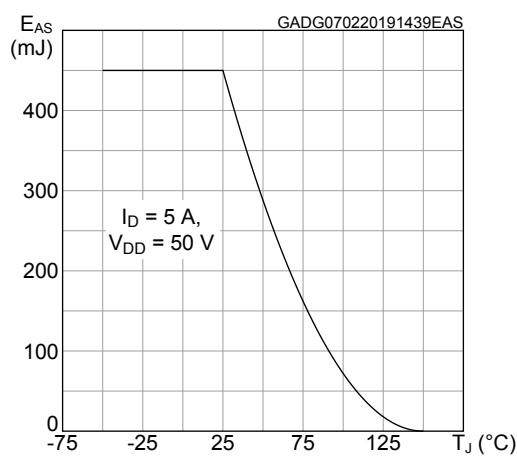
**Figure 5. Safe operating area for TO-247**



**Figure 6. Thermal impedance for TO-247**

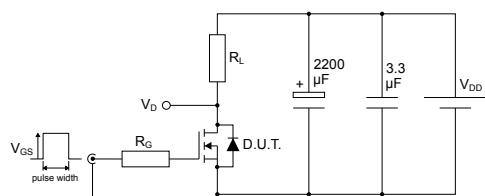


**Figure 7. Output characteristics**

**Figure 8. Transfer characteristics**

**Figure 9. Gate charge vs gate-source voltage**

**Figure 10. Static drain-source on-resistance**

**Figure 11. Capacitance variations**

**Figure 12. Normalized gate threshold voltage vs temperature**


**Figure 13. Normalized on-resistance vs temperature**

**Figure 14. Source-drain diode forward characteristics**

**Figure 15. Normalized V<sub>(BR)DSS</sub> vs temperature**

**Figure 16. Output capacitance stored energy**

**Figure 17. Maximum avalanche energy vs temperature**


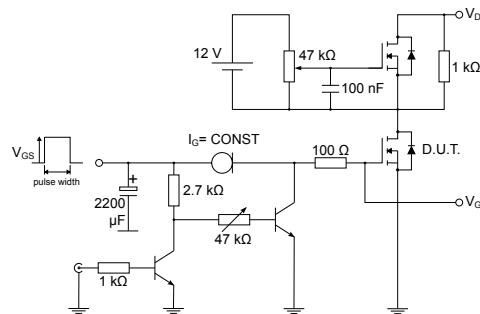
### 3 Test circuits

**Figure 18.** Test circuit for resistive load switching times



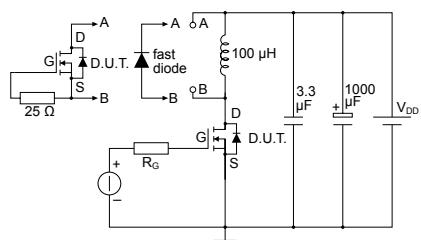
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**Figure 19.** Test circuit for gate charge behavior



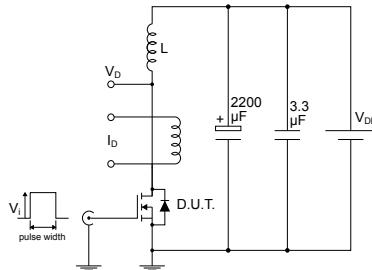
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**Figure 20.** Test circuit for inductive load switching and diode recovery times



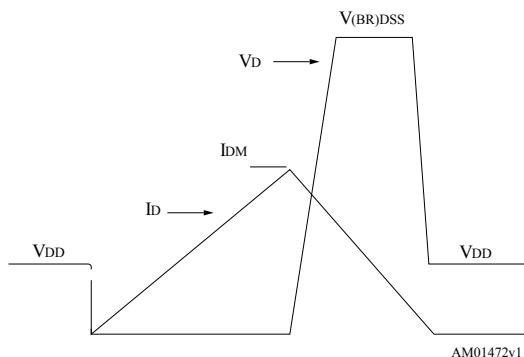
AM01470v1

**Figure 21.** Unclamped inductive load test circuit



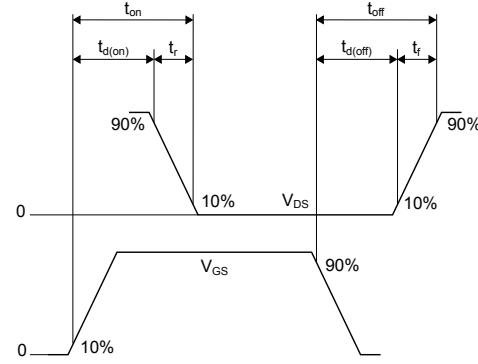
AM01471v1

**Figure 22.** Unclamped inductive waveform



AM01472v1

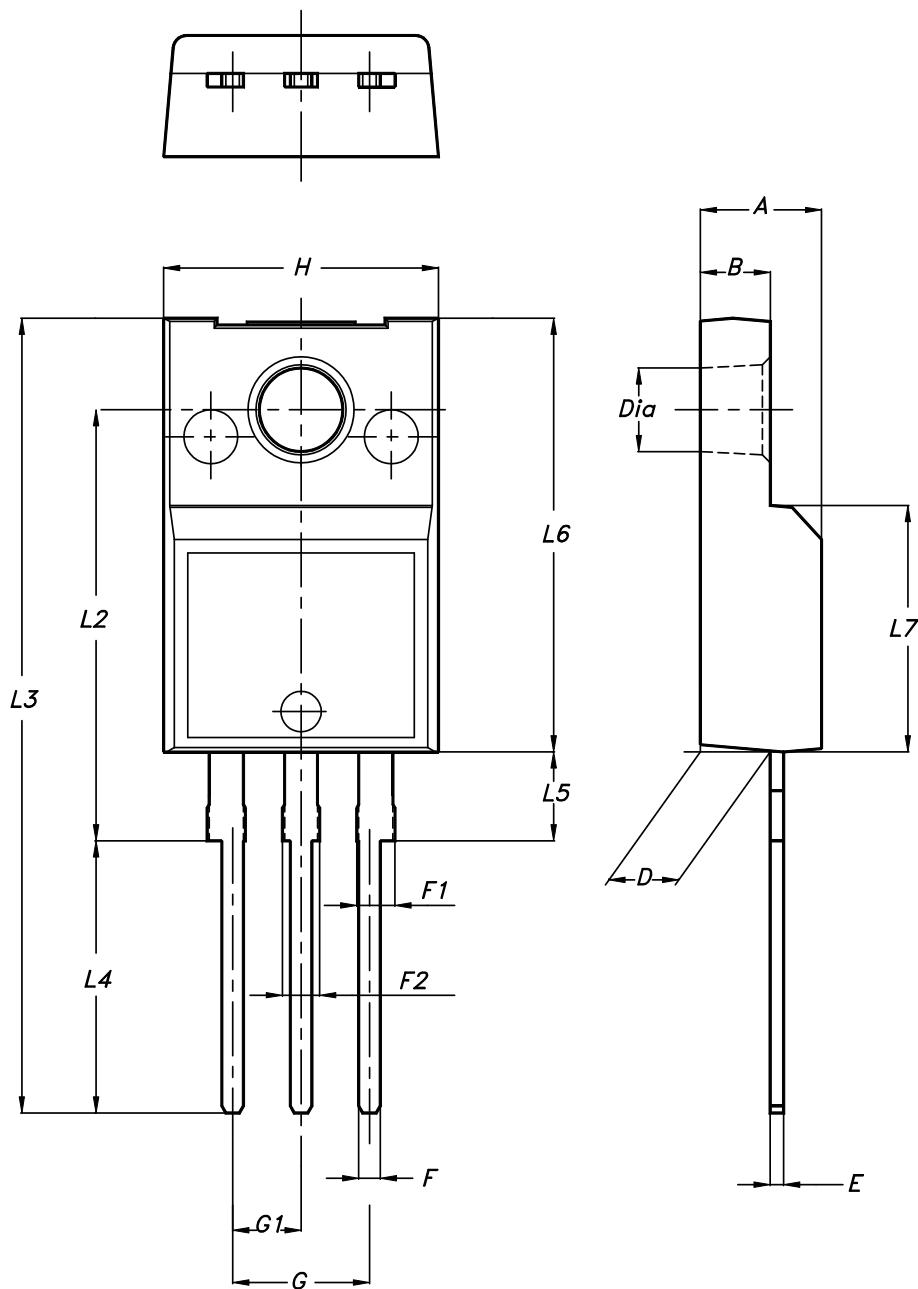
**Figure 23.** Switching time waveform



AM01473v1

**4****Package information**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**4.1 TO-220FP package information****Figure 24. TO-220FP package outline**

7012510\_Rev\_13\_B

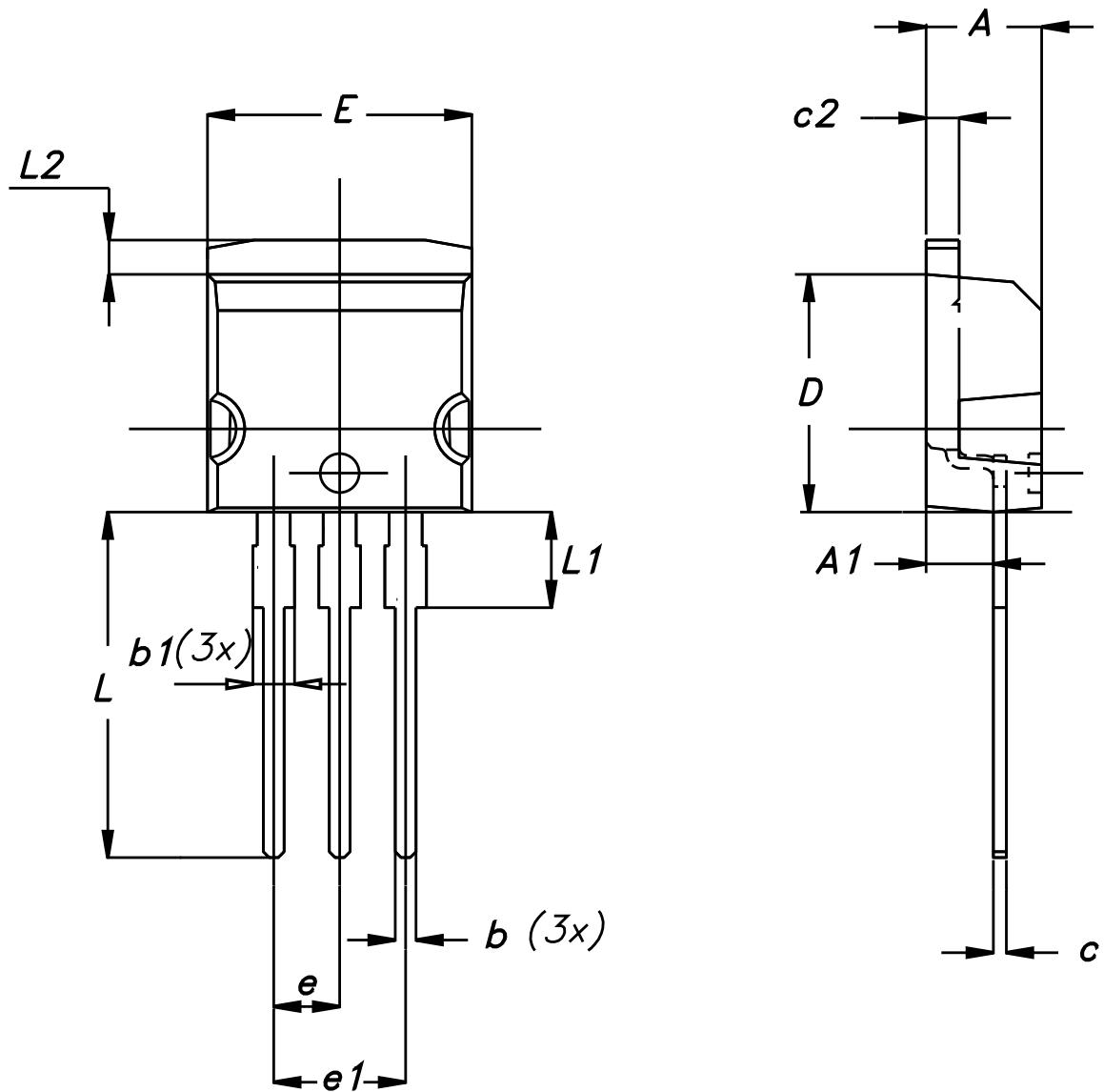


Table 8. TO-220FP package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

## 4.2 I<sup>2</sup>PAK package information

Figure 25. I<sup>2</sup>PAK package outline



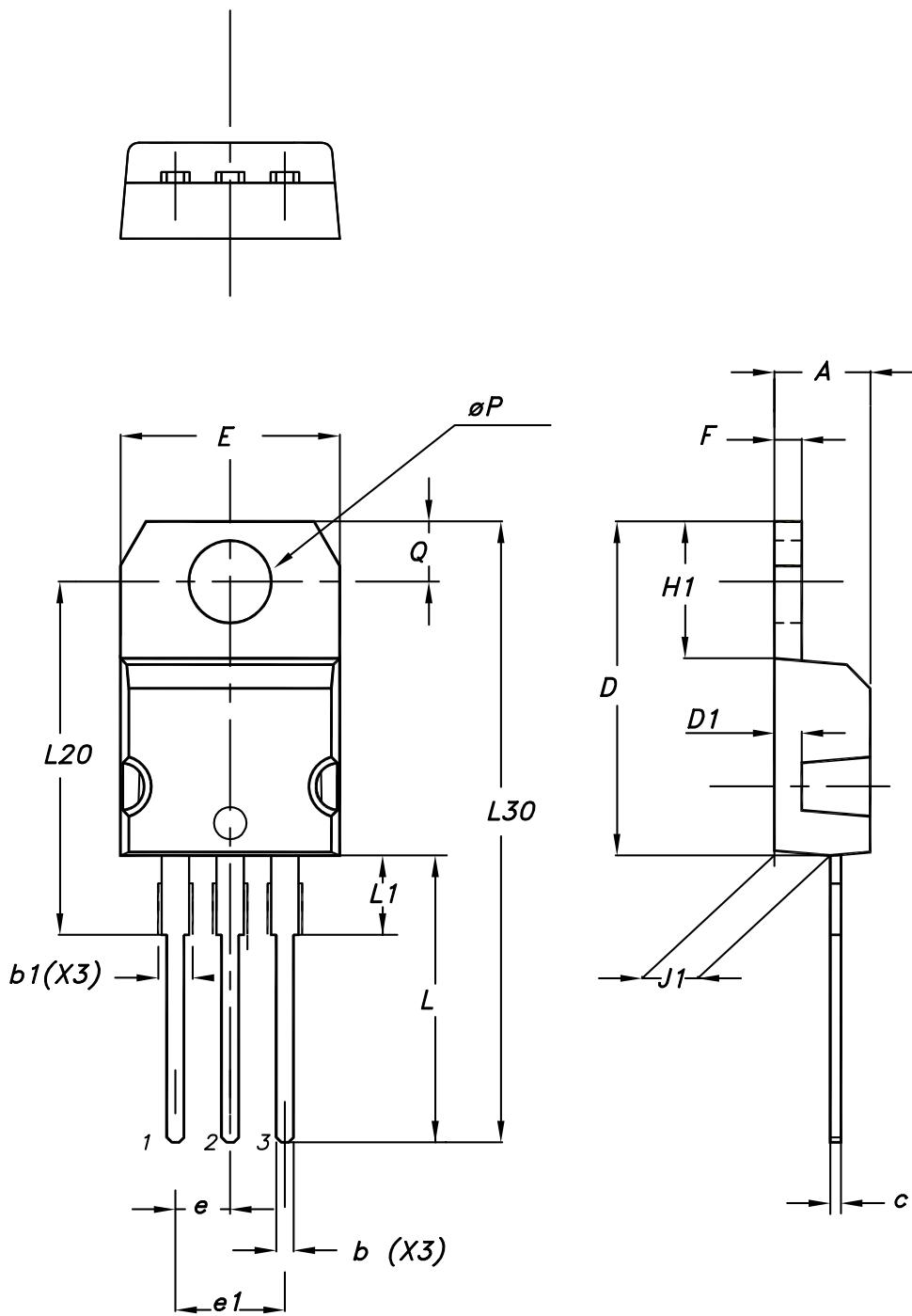
0004982\_Rev\_H

**Table 9.** I<sup>2</sup>PAK package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40	-	4.60
A1	2.40	-	2.72
b	0.61	-	0.88
b1	1.14	-	1.70
c	0.49	-	0.70
c2	1.23	-	1.32
D	8.95	-	9.35
e	2.40	-	2.70
e1	4.95	-	5.15
E	10	-	10.40
L	13	-	14
L1	3.50	-	3.93
L2	1.27	-	1.40

#### 4.3 TO-220 type A package information

Figure 26. TO-220 type A package outline



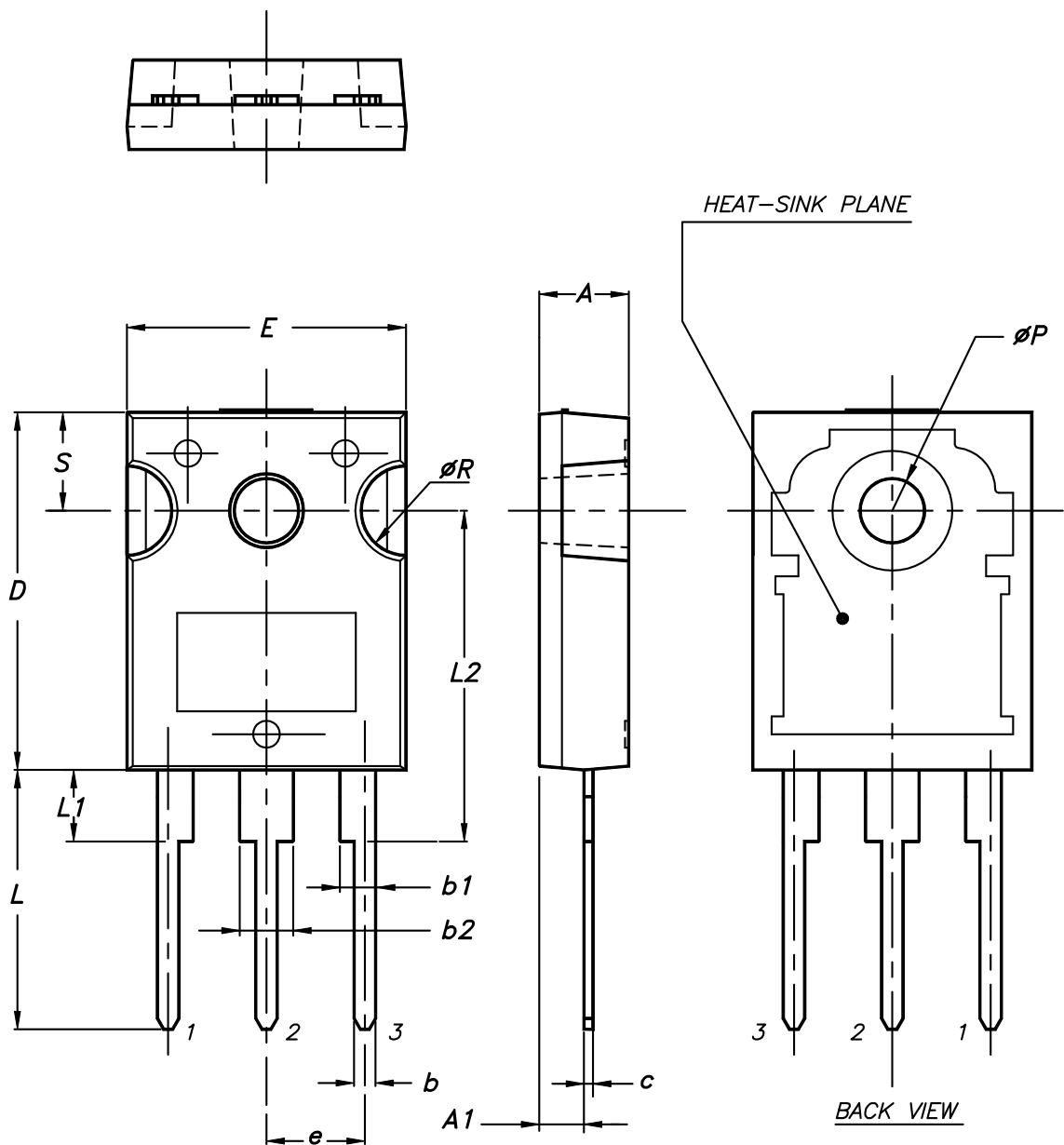
0015988\_typeA\_Rev\_22

Table 10. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

#### 4.4 TO-247 package information

Figure 27. TO-247 package outline



0075325\_9

**Table 11.** TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

## 5 Ordering information

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**Table 12. Order codes**

Order code	Marking	Package	Packing
STF33N60M2	33N60M2	TO-220FP	Tube
STI33N60M2		I <sup>2</sup> PAK	
STP33N60M2		TO-220	
STW33N60M2		TO-247	

## Revision history

**Table 13. Document revision history**

Date	Version	Changes
13-Sep-2013	1	First release.
19-Nov-2013	2	Modified: $R_{DS(on)}$ and $I_D$ values in cover page Modified: values in <i>Table 4</i> Modified: $R_{DS(on)}$ typical and maximum values in <i>Table 5</i> , the entire typical values in <i>Table 6, 7 and 8</i> Added: <i>Section 2.1: Electrical characteristics (curves)</i> Minor text changes
14-Jun-2019	3	Removed maturity status indication from cover page. Updated title, features and description. Updated <i>Table 3. Avalanche characteristics</i> . Added <i>Figure 17. Maximum avalanche energy vs temperature</i> . Minor text changes

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